Product Information

Lead-free electronic solder FELDER-ISO-Tin® „Sn99Ag+REFILL“

Lead-free refill solder for selective and wave soldering units, RoHS conformity acc. 2011/65/EU
Sn99,6Ag0,3NiGe acc. to Fuji-Pat. No. DE19816671C2, US6179.935, JP3296289
Sn99,6Ag0,3Ni (Ge) according to DIN EN 9452:2014

Item-No.: 551282 ….

Application

In order to compensate the entry of copper into the lead-free alloy Sn99Ag+ in wave soldering and selective soldering units we recommend Sn99Ag+ Refill. Hereto a regular control of the solder bath is unavoidable.

Properties

As most of the PCBs and components have copper-plated conducting paths and connections copper is flushed into the solder bath by the soldering process. In fact Sn99Ag+ has a lower dealloying quote of copper as other lead-free solders, nevertheless a copper level compensation is necessary.

Alloy:	Sn99,6Ag0,3NiGe
Melting point:	reduces in the solder bath to 217 – 227 ° C!

Impurities / Tolerances

Sn99Ag+

Element	**Ag**	**Al**	**As**	**Bi**	**Cd**	**Cu**	**Fe**
content (%)	0,3±0,1	0,001	0,03	0,06	0,002	0,7±0,2	0,02
Element	**Ge**	**Ni**	**Pb**	**Sb**	**Sn**	**Zn**	
content (%)	0,01 - 0,015	0,06±0,02	0,07	0,1	Rest	0,001	

Delivery Forms

400 g - rods, 330 x 20 x 10 mm,
3,5 kg – blocks with hanging hole 545 x 47 x 20 mm.
Also deliverable as massive wire on spools and wire cuts for first filling.

Other alloys are included in our standard delivery program.

Storage

Stored at constant indoor climate durable for an unlimited period!

Status: 03/2017